CALL FOR PAPERS

IMPORTANT DATES

CALL FOR PAPERS DEADLINES

October 24, 2022
Regular Paper Submission

December 5, 2022
Transactions Paper Submissions

December 19, 2022
Author Notification

February 4, 2023
Final Manuscript Submission

TOPICS OF INTEREST

The IEEE International Symposium on Circuits and Systems (ISCAS) is the flagship conference of the IEEE Circuits and Systems (CAS) Society and the world's premiere forum for researchers in the active fields of theory, design and implementation of circuits and systems. This is accomplished through technical conference sessions, poster sessions, live demonstration sessions, and publication of conference papers. ISCAS 2023 will be driven by the theme “Technology Disruption and Society” aiming to emphasize the potential of the CAS Society to find innovative solutions to challenges facing society today.

This year’s meeting will highlight the following innovation themes:

- Artificial Intelligence & Deep Learning
- Big Data Processing
- Internet of Things
- Distributed and Decentralized Systems
- Intelligent Video Analytics and Vision Systems
- Zettabyte Communication Infrastructure
- Storage Class Memories and Computational Storage
- Personalized Healthcare Systems
- Brain: Innovative NeuroTechnologies
- Disaster and Pandemic Prevention and Mitigation
- Green and Sustainable Computing and Systems
- Technologies for Responsible, Fair and Ethical IT

Collecting contributions in all areas of Circuits and Systems, including but not limited to:

- Analog and Mixed Signal Circuits and Systems
- Digital Integrated Circuits and Systems
- Power and Energy Circuits and Systems
- Sensory Circuits and Systems
- Nonlinear Systems and Circuit Theory
- Digital Signal Processing
- Multimedia Systems and Applications
- Communications Circuits and Systems
- Biomedical Circuits and Systems
- Neural Networks and Neuromorphic Engineering
- Beyond CMOS: Nanoelectronics and Heterogeneous System Integration
- Education in Circuits and Systems

Paper Submission

Selected papers will be invited for possible publication either in the IEEE Transaction on Circuits and Systems – Part I, in the IEEE Transaction on Circuits and Systems – Part II, or in the IEEE Transaction on Biomedical Circuits and Systems.

About Monterey

Picture seaside cliffs and pristine beaches, where you might spot whales, sea otters and migrating birds. From famous writers' haunts to Spanish Missions, the history here is just as fascinating as the geography. Aside from the epic scenery, you'll savor unforgettable flavors from the area's award-winning food and wine scene. Plus, there are limitless opportunities for recreation, including world-class golf, shopping, kayaking, hiking and only 70 miles from Silicon Valley.

Please visit: iscas2023.org
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